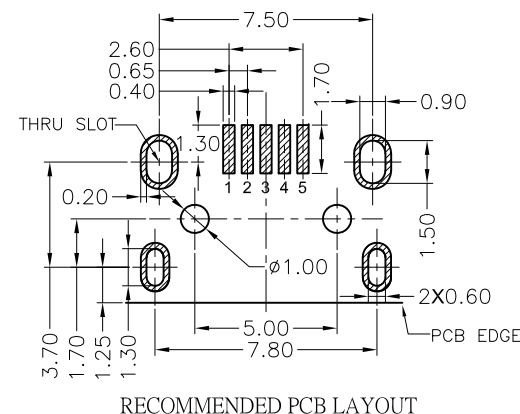
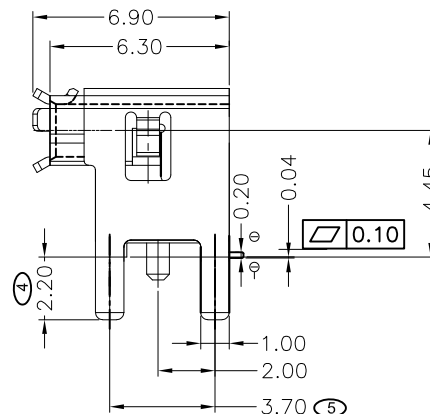
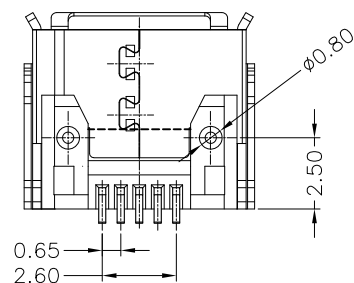
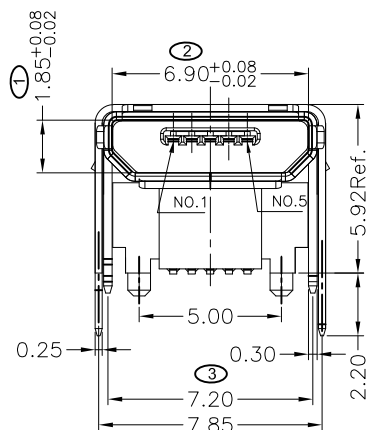
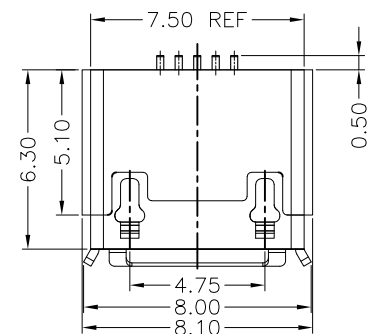




1. MATERIAL
HOUSING: LCP,UL94V-0,BLACK
CONTACT: COPPER ALLOY,T=0.20
SHELL: STAINLESS STEEL,T=0.3
COVER: STAINLESS STEEL,T=0.25
2. FINISH
CONTACT: 50U" MIN NICKEL UNDERPLATING OVERALL
GOLD PLATING SELECTIVE ON CONTACT AREA
50U" MIN TIN PLATING ON SOLDER TAIL
SHELL: 40U" MIN NICKEL UNDERPLATING OVERALL
COVER: 40U" MIN NICKEL UNDERPLATING OVERALL
3. ELECTRICAL
CURRENT: 1.0A
VOLTAGE: 30V
CONTACT RESISTANCE: 50 MILLIOHMS MAX.
DIELECTRIC WITHSTANDING VOLTAGE: 500V AC
INSULATION RESISTANCE: 100 MEGOHMS MIN.
4. MECHANICAL
MATING FORCE: 35N MAX.
UNMATING FORCE: 10N MIN,INITIAL.
8~20N AFTER 10000 CYCLES.
DURABILITY: 10000 CYCLES

※ SIGN "ⓧ" IS IMPORTANCE DIMENSION

KEM 奇速科技有限公司
Qi-Speed Technology CO., LTD.

產品名稱:
PRODUCT NAME
MICRO USB 5P B-F SMT CL=4.45
有邊(脚长2.2)

單位: mm	繪圖	設計	審核	核准	料號:KMR1-MD05SMB1N-080
比例:	DRAWING	DESIGNED	CHECKED BY	APPROVAL BY	PART NUMBER
公差: .X ±0.38 .XX ±0.25 .XXX ±0.13	JOHNY	JOHNY	LUKE	JAMES	圖號:KMR1-MD05SMB1N-080-1 DRAWING NO
日期: 2018/1/11					版本: REV. 0

版本	修改事項	修改日期